



**TAIYO KOGYO CO., LTD.**  
**Printed Circuit Company**

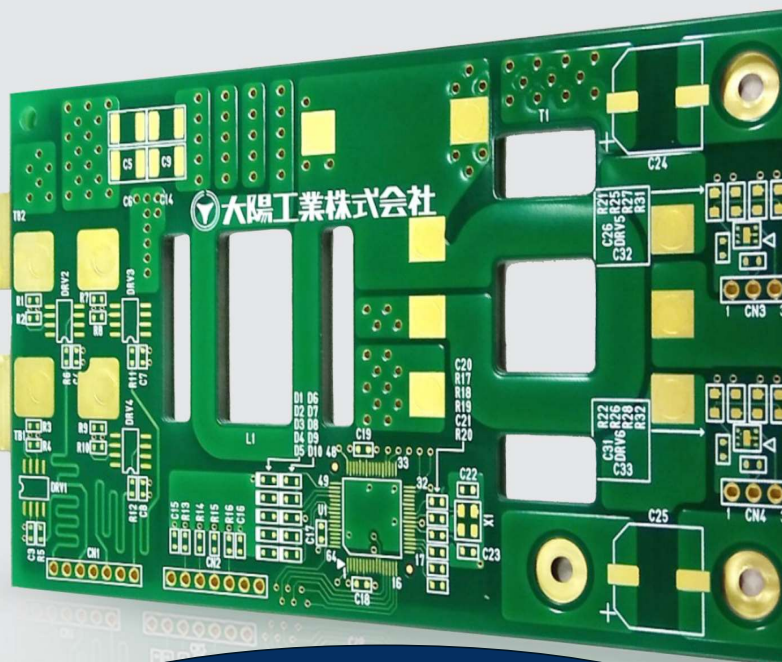
Confidential UB001.004

Our technology and capabilities are taking the leading part in the latest high-end technology on the rise of EV and e-VTOL since high current PCB are on high demand.

**We specialize in**



- Ultra Thick Copper PCBs
- Combination PCBs
- Bus Bar Embedded PCBs
- Copper Inlay PCBs



**Heat Dissipation**

**High Current**

**Applications  
Examples**

- eVTOL
- Automotive / EV
- Humanoid Robot
- Power Supplies
- Power Electronics
- BMS

For more detail, visit us at  
<https://www.taiyo-technologies.jp/solution/pcb-en>

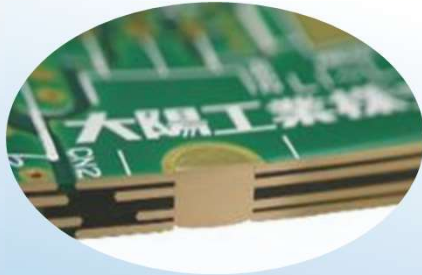




# TAIYO KOGYO CO., LTD. Printed Circuit Company

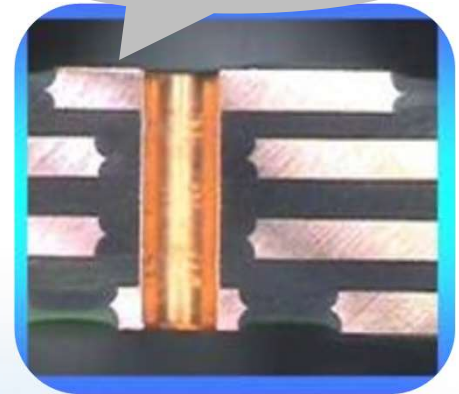
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## Ultra Thick Copper PCB

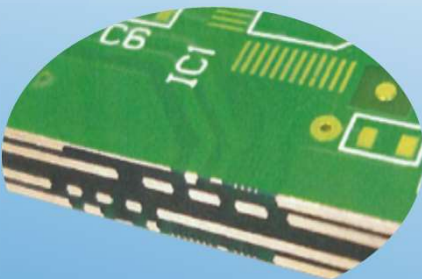


- Copper foil thickness: 8.6oz / 11.4oz / 14.3oz (using rolled copper foil)
- Number of Layers: 2-6 Layers (\*depending on copper foil thickness)
- Board thickness: 0.051"-0.137" (1.3-3.5 mm)
- Available: IVH / Combined with less than 6.8oz copper is available
- UL Certified

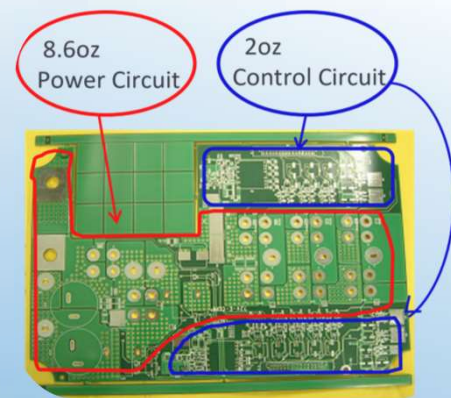
14.3 oz for all layers  
Board Thickness  
0.125" (3.2mm)



## Combination PCB



- Copper foil thickness: 8.6oz & 2oz copper on the very same layer
- Number of Layers: 2- 6 Layers
- Board thickness: 0.051"-0.137" (1.3 - 3.5 mm)
- Available: IVH / Combined with less than 11.4oz, 14.3oz, and 6.8oz copper is available
- Next generation Power devices GaN, SiC
- UL Certified



## Bus Bar Embedded PCB

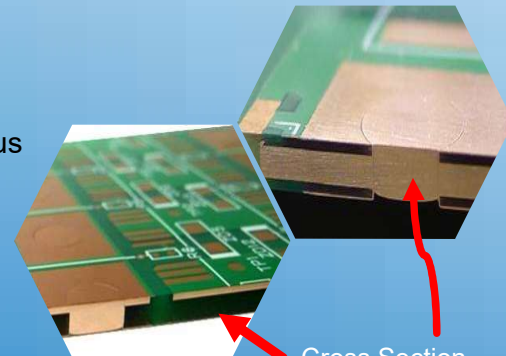


Bus Bar Terminal with Resin



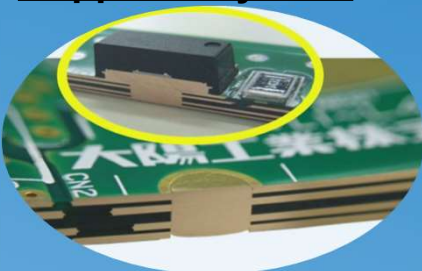
Pure Bus Bar Terminal

- Bus Bar thickness: 14.3 / 22.8 / 28.5 / 57.1oz
- Board thickness: 3.5mm max
- Basic Structure : bus bar resin and pure bus bar PCB
- Bus bar Terminal :available for both inner and outer layers
- High current and high voltage, with higher electrical performance, efficiency, space savings, and heat dissipation

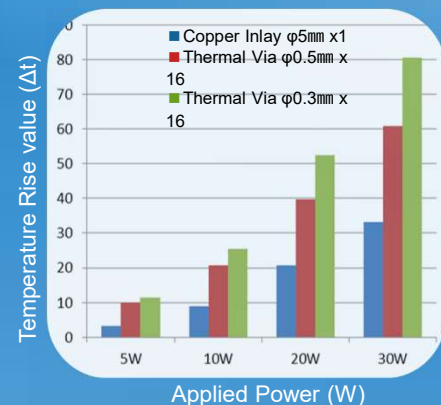


Cross Section

## Copper Inlay PCB



- Available for all copper foil thickness
- Diameters of inlay: 0.118"/0.157"/0.196"/0.236" (3 / 4 / 5 / 6 mm)
- Highly efficient heat dissipation for power semiconductors such as SiC and GaN
- Heat dissipation for multi-layer and double-layer PCB by pressing copper inlay into PCB



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